

0.6.1 sub revision:

Simple improvements that make the boards easier to solder:

- black silkscreen, white solder mask
- improved footprints, better text positioning
- removing lots of 0 Ohm jumpers that are really used
- PCBs are 1mm thick now

Mechanical changes:

- removed speaker hole(RF), as the Chinese case uses low profile speaker

Schematics changes:

- thermal sensor and LO heater removed from the RF board
- Potato chip divider in LO(U11) instead of 74AC74
- Parallel interface for the LCD no longer supported
- Six pin Nucleo debug connector for easy programming/development(UI)